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ABSTRACT OF THE DISCLOSURE

The present invention discloses a conductive composition, comprising: (a) at least one polymer; (b) at least one conductive filler, dispersed in the polymer; and (c) a coupling agent, applied to improved the adhesion between the polymer and the conductive filler and having a structure as follows:

$$(R^{1} O_{m}M - (OR^{2})_{a})_{n}$$

wherein M represents a metal atom or silicon; R^1 and R^2 represent a substituted or unsubstituted alkyl group; X represents sulfur or phosphorous; and a, m and n represent integers of 0 to 2.